



# XtremeSpeed™ RO1200™ Series Circuit Materials

Extremely Low Loss  
Digital Circuit Laminates

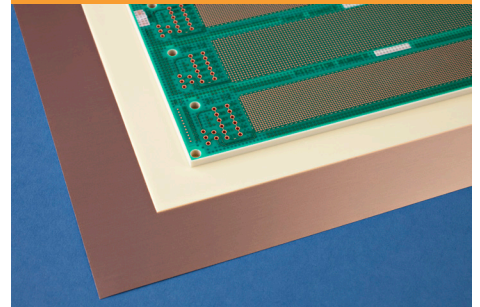


XtremeSpeed™ RO1200™ extremely low loss digital circuit materials are ceramic-filled laminates reinforced with woven fiberglass. These materials are engineered to offer exceptional electrical performance and mechanical stability for the most demanding high speed applications.

XtremeSpeed RO1200 series laminates combine the surface smoothness of a non-woven PTFE laminate, for finer line etching tolerances, with the rigidity of a woven-glass PTFE laminate. These materials can be fabricated into printed circuit boards using standard PTFE circuit board processing techniques as described in the application note, XtremeSpeed RO1200 Extremely Low Loss Digital Laminate Quick Reference Processing Guide.

XtremeSpeed RO1200 series laminates are manufactured under an ISO 9001 certified quality system.

Data Sheet



## Features and Benefits:

Superior signal integrity

- Low dielectric constant
- Low dissipation factor
- Low profile copper for reduced insertion loss

Excellent thermal/mechanical performance characteristics

- Ideal for high layer count structures
- Suitable for lead free processing
- Td: 500°C (TGA)
- Low CTE

Woven glass reinforcement

- Improved rigidity for ease of handling
- Spread glass for reduced signal skew

## Typical Applications:

- Core/edge IP routers and switches
- High performance computing (HPC) servers, switching and storage
- Backplanes
- Automated test equipment (ATE)

Property	Typical Value RO1200	Direction	Unit	Condition	Test Method
Dielectric Constant, Process	3.05	Z		10 GHz 23°C	IPC-TM-650 2.5.5.5
Dielectric Constant, Design <sup>[1]</sup>	3.05	Z		1 GHz - 20 GHz	Differential Phase Length Method
Dissipation Factor, tan δ	0.0017 Max	Z		10 GHz 23°C	IPC-TM-650 2.5.5.5
Dimensional Stability	0.22	X,Y	mil/inch	after etch +E/150	IPC-TM-650 2.4.39
Volume Resistivity	1.3 x 10 <sup>7</sup>	Z	MΩ•cm	C-96/35/90	IPC-TM-650 2.5.17.1
Surface Resistivity	2.5 x 10 <sup>6</sup>	Z	MΩ	C-96/35/90	IPC-TM-650 2.5.17.1
Dielectric Strength	630		V/mil		IPC-TM-650 2.5.6.2
Moisture Absorption	0.03		%	E-1/105+D-48/50	IPC-TM-650 2.6.2.1
Specific Heat	0.93 (0.22)		J/g/K (BTU/lb/°F)		Calculated
Thermal Conductivity	0.42	Z	W/mK		ASTM D5470
Coefficient of Thermal Expansion	8	X,Y	ppm/°C	-55°C to 288°C	IPC-TM-650 2.4.41
	30	Z			IPC-TM-650 2.4.24
Time to Delamination	>60		Minutes	260°C	IPC-TM-650 2.4.24.1
	>60			288°C	
Td	500		°C	TGA	IPC-TM-650 2.4.24.6
Density	2.1		g/cm <sup>3</sup>	C-24/23/50	ASTM D792
Copper Peel Strength	>4.5		lbs/in	1 oz ED Foil	IPC-TM-650 2.4.8
Flammability	V-0				UL 94
Lead Free Process Compatible	YES				

NOTE:  
 [1] The design Dk is an average number from several different tested lots of material and on the most common thickness/s. If more detailed information is required please contact Rogers Corporation or refer to Roger's technical reports on the Rogers Technology Support Hub at [www.rogerscorp.com/techub](http://www.rogerscorp.com/techub)

Standard Thickness		Standard Panel Size	Standard Copper Cladding
0.003" (0.076mm)	0.007" (0.178mm)	12" X 18" (305 X 457mm)	½ oz. (17µm) RA copper foil (AH) 1 oz. (35µm) RA copper foil (A1) 2 oz. (70µm) ED (H2) & RT copper foil (S2)
0.004" (0.102mm)	0.008" (0.203mm)	24" X 18" (610 X 457mm)	
0.005" (0.127mm)	0.010" (0.254mm)	Additional panel sizes available upon request	
0.006" (0.152mm)			

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